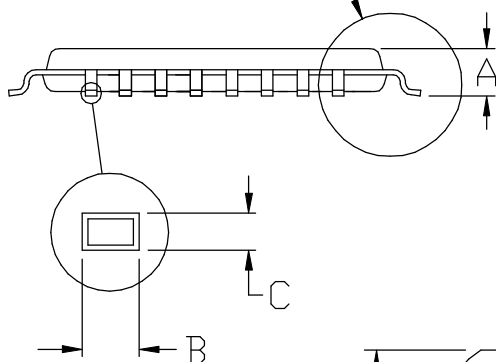


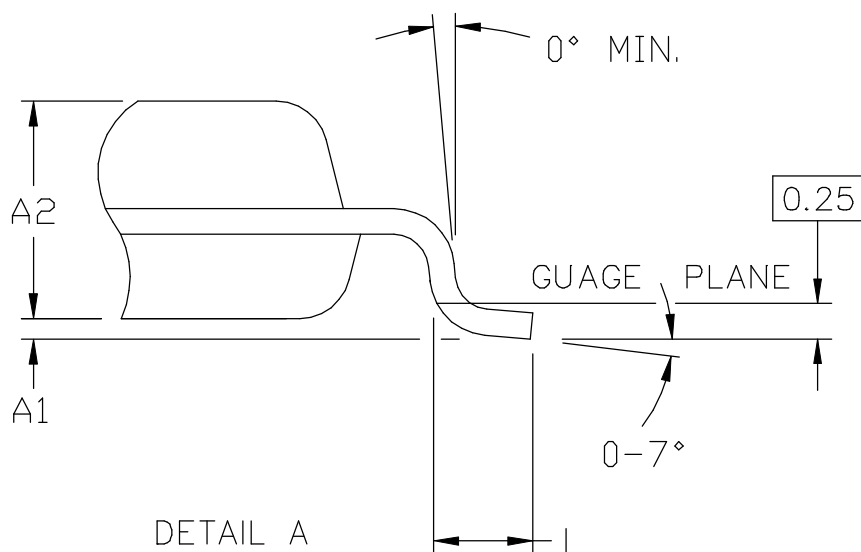
SEE DETAIL "A"



DIM	MIN	MAX
A	—	1.20
A1	0.05	0.15
A2	0.95	1.05
D	8.80	9.20
D1	7.00	BSC
E	8.80	9.20
E1	7.00	BSC
L	0.45	0.75
e	0.80	BSC
B	0.30	0.45
C	0.09	0.20


NOTES:

1. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH, BUT DO NOT INCLUDE MOLD PROTRUSION; ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE.
2. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
3. ALLOWABLE DAMBAR PROTRUSION IS 0.08 MM TOTAL IN EXCESS OF THE B DIMENSION; AT MAXIMUM MATERIAL CONDITION. PROTRUSION NOT TO BE LOCATED ON LOWER RADIUS OR FOOT OF LEAD.
4. CONTROLLING DIMENSIONS: MILLIMETERS.



DETAIL A

DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE		 Dallas Semiconductor TITLE MARKETING OUTLINE, 32 LD. TQFP 7 X 7 X 1.00 MM BODY			
DOC. CONTROL:							
ENGR. MGR:							
MFG. ENGR:							
CHECKED BY:							
DRAWN BY:				SIZE A	FSCM NO	PART NO.	REV A
DO NOT SCALE DWG.				SCALE N/A		SHEET 1 OF 1	